IEEE ICMA 2026

2026 IEEE International Conference on Mechatronics and Automation

August 2-5, 2026, Changchun, China

Co-sponsors: IEEE Robotics and Automation Society, Jilin University, SUSTech and HEU

Technical Co-sponsors: NSFC, CAA, RSJ, JSME, SICE, JSPE, UEC, BIT, UESTC

Call for Papers

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The 2026 IEEE International Conference on Mechatronics and Automation (ICMA 2026) will take place in Changchun, China from August 2 to August 5, 2026. A renowned ancient city in China, Changchun is situated in northeastern China. As the capital of Jilin province, Changchun is known as the cradle of new China's automobile industry, optoelectronics technology and biological technology, applied chemistry and so on. As the host city of IEEE ICMA 2026, Changchun not only provides the attendees with a great venue for this event, but also an unparalleled experience in Chinese history and culture. You are cordially invited to join us at IEEE ICMA 2026 in Changchun to live this unique experience. The objective of IEEE ICMA 2026 is to provide a forum for researchers, educators, engineers, and government officials involved in the general areas of mechatronics, robotics, automation and sensors to disseminate their latest research results and exchange views on the future research directions of these fields.

The topics of interest include, but not limited to the following:

- Intelligent mechatronics, robotics, biomimetics, automation, control systems,
- Opto-electronic elements and Materials, laser technology and laser processing
- Elements, structures, mechanisms, and applications of micro and nano systems
- Teleoperation, telerobotics, haptics, and teleoperated semi-autonomous systems
- Sensor design, multi-sensor data fusion algorithms and wireless sensor networks
- Biomedical and rehabilitation engineering, prosthetics and artificial organs
- Control system modeling and simulation techniques and methodologies
- AI, intelligent control, neuro-control, fuzzy control and their applications
- Industrial automation, process control, manufacturing process and automation

Contributed Papers: All papers must be submitted in PDF format prepared strictly following the IEEE PDF Requirements for Creating PDF Documents for IEEE Xplore. The standard number of pages is 6 and the maximum page limit is 8 pages with extra payment for the two extra pages. See detailed instructions in the conference web site. All papers accepted will be indexed by EI and all conference content will be submitted for inclusion into IEEE Xplore®. Extensions of selected papers will be published in a regular or a special issue of the journals of **IJMA**.

Organized Sessions: Proposals with the title, the organizers, and a brief statement of purpose of the session must be submitted to an OS Chair by April 10, 2026.

Tutorials & Workshops: Proposals for tutorials and workshops that address related topics must be submitted to one of the Tutorial/Workshop Chairs by May 1, 2026.

Important Dates:

April 10, 2026	**Full papers and organized session proposals**
May 1, 2026	**Proposals for tutorials and workshops**
May 15, 2026	**Notification of paper and session acceptance**
June 1, 2026	**Submission of final papers in IEEE PDF format**

For detailed up-to-date information, please visit the IEEE ICMA conference website at:

http://2026.ieee-icma.org

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